



Title of Change:	Update to FPCN22814Z - announcing early implementation of Test Platform conversion from TMT to uFlex.
Proposed Changed Material First Ship Date:	07 Dec 2020
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local ON Semiconductor Sales Office or Patrick.VandePontseele@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or PCN.samples@onsemi.com Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	N/A
PPAP Availability Date:	N/A
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Description and Purpose:	
Due to a capacity constraint, we are implementing this change earlier than originally announced in FPCN22814Z.	
The change will be effective immediately.	
FPCN22814Z released in February announced The change is a test program conversion from the TMT test platform to the uFlex test platform.	
There are no product material changes as a result of this change.	
There is no product marking change as a result of this change.	



Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Carmona, Philippines	None	
Marking of Parts/ Traceability of Change:	NA	
Reliability Data Summary: Reliability data is not impacted.		
Electrical Characteristics Summary: Electrical characteristics are not impacted.		
List of Affected Parts: <i>Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.</i>		
Current Part Number	New Part Number	Qualification Vehicle
NCV7342D10R2G	NA	NCV7342D10R2G



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV7342D10R2G	0CANV-001-XTP	NCV7342D10R2G	NA	